PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5760008

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the TYPOGRAPHICAL ERROR IN 1ST INVENTOR'S LAST NAME previously recorded on Reel 036403 Frame 0354. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNOR'S INTEREST.

CONVEYING PARTY DATA

Name	Execution Date
KUO-CHENG CHIANG	09/18/2019
CHI-WEN LIU	09/18/2019
YING-KEUNG LEUNG	09/17/2019

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	8, Li-Hsin Rd. 6, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14739294

CORRESPONDENCE DATA

Fax Number: (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 972-732-1001
Email: docketing@slatermatsil.com
Correspondent Name: SLATER MATSIL, LLP
Address Line 1: 17950 PRESTON RD., SUITE 1000
Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM15-0147
NAME OF SUBMITTER:	MARANDA BRALLEY
SIGNATURE:	/MARANDA BRALLEY/
DATE SIGNED:	10/08/2019

Total Attachments: 6
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source=TSM15-0147 Recordation of Assignment 2015-08-24#page5.tif
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UNITED STATES PATENT AND TRADEMARK OFFICE
UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

AUGUST 25, 2015

PTAS

SLATER & MATSIL, L.L.P.
17950 PRESTON RD., SUITE 1000
DALLAS, TX 75252

503449056

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

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RECORDATION DATE: 08/24/2015
REEL/FRAME: 036403/0354
NUMBER OF PAGES: 2

BRIEF: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

DOCKET NUMBER: TSM15-0147

ASSIGNOR:
CHING, KUO-CHENG
DOC DATE: 08/19/2015

ASSIGNOR:
LIU, CHI-WEN
DOC DATE: 08/19/2015

ASSIGNOR:
LEUNG, YING-KEUNG
DOC DATE: 08/19/2015

ASSIGNEE:
TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK
HSIN-CHU, TAIWAN 300-77

APPLICATION NUMBER: 14739294
FILING DATE: 06/15/2015
PATENT NUMBER:
ISSUE DATE:
TITLE: WRAP AROUND SILICIDE FOR FINFETS

ASSIGNMENT RECORDATION BRANCH
PUBLIC RECORDS DIVISION

United States Patent and Trademark Office

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Confirmation Receipt

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KUO-CHENG CHING	08/19/2015
CHI-WEN LIU	08/19/2015
YING-KEUNG LEUNG	08/19/2015

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14739294

CORRESPONDENCE DATA

Fax Number: (972)732-9218
Phone: 972-732-1001
Email: docketing@slater-matsil.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: SLATER & MATSIL, L.L.P.
Address Line 1: 17950 PRESTON RD., SUITE 1000
Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM15-0147
NAME OF SUBMITTER:	LISETTE REYES-WASHINGTON
Signature:	/Lisette Reyes-Washington/
Date:	08/24/2015
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 1
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RECEIPT INFORMATION

EPAS ID: PAT3495682
Receipt Date: 08/24/2015

Return to home page

| .HOME | INDEX| SEARCH | eBUSINESS | CONTACT US | PRIVACY STATEMENT

ATTORNEY DOCKET NO.
TSM15-0147

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Wrap Around Silicide for Finfets			
SIGNATURE OF INVENTOR AND NAME	✓ Kuo-Cheng Ching Kuo-Cheng Ching	✓ Chi-Wen Liu Chi-Wen Liu	✓ Ying-Keung Leung	
DATE	2015/8/19	✓2015/8/19	✓ 19/8/2015	
RESIDENCE	Zhubei City, Taiwan	Hsin-Chu, Taiwan	Hsinchu, Taiwan	

ATTORNEY DOCKET NO.
TSM15-0147

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78, Taiwan, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Wrap Around Silicide for FinFETs			
SIGNATURE OF INVENTOR AND NAME	Kuo-Cheng Chiang	Chi-Wen Liu	Ying-Keung Leung	
DATE	2019/9/18	2019/9/18	2019/9/17	
RESIDENCE	Zhubei City, Taiwan	Hsinchu, Taiwan	Hsinchu City, Taiwan	